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Deposition Rates on PVD75 Magnetron Sputterer

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Deposition Rates on PVD75 DC/RF Magnetron Sputterer (Graduate Student Fellow Program)

Prepared by Dhruv Turakhia (2/26/2015)

SiO₂

- Base Pressure: less than 5×10^{-7} Torr
- Process Ar Pressure: 3 mTorr
- RF Power:
- Deposition Rate: 1.2 ± 0.2 nm/min
- Thickness measurement: P7 stylus profiler

Ni

- Base Pressure: less than 5×10^{-7} Torr
- Process Ar Pressure: 3 mTorr
- DC Power: 400 W
- Deposition Rate: 21.1 ± 1.1 nm/min
- Thickness measurement: P7 stylus profiler

Al

- Base Pressure: less than 5×10^{-7} Torr
- Process Ar Pressure: 3 mTorr
- DC Power: 400 W
- Deposition Rate: 11.0 ± 2.1 nm/min
- Thickness measurement: P7 stylus profiler

Al Deposition

